

Shinkawa to Release Wide Area Handling High-speed Wafer Bump Bonder: SBB-5200

Shinkawa Ltd. (President: Takashi Nagano, Headquarters: 51-1, Inadaira 2-chome, Musashi-Murayama-shi, Tokyo, Japan) has started accepting new orders for the SBB-5200, a wide area handling high-speed wafer bump bonder.

In the coming IoT age, it is expected that the number of sensors connected to the Internet will be 1 trillion. The SBB-5200 is developed for production of electronic devices including RF, crystal types, and MEMS which are incorporated into various sensors.

This model achieves high-speed bump bonding (30ms/bump) based on Wire Bonder model UTC-5000, and increases productivity by incorporating two wafer stages with a temperature up/down control function.



【Features of SBB-5200】

- (1) Capable of handling up to 6-inch wafers by equipping with wafer rotary stage
- (2) Wafer stage(s) with temperature up/down control function
- (3) Capable of handling maximum bonding force of 4.9N, and wire size of $\phi 15\text{--}32\ \mu\text{m}$
- (4) High-accuracy bonding achieved by adopting Shinkawa's unique Non-vibration System (NVS) and Reference Positioning System (RPS) technologies

【High-speed bump bonder SBB-5200】

In the future, an automatic wafer loader will be available, and 8-inch wafer handling capability (1-wafer stage) will be developed.

- Other Product Line-ups
Wire Bonders, Die Bonders, Flip Chip Bonders

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